

## ABSTRACT

The invention relates to a method for laser micro-dissection wherein a set cutting line is marked in relation to an object which is to be cut out in a microscopic preparation and the object is subsequently cut out by means of a relative movement between a laser beam and the preparation. The method is characterized in that at least one electronic image of at least one picture detail of the preparation is captured, the picture detail is processed analytically, wherein at least one object to be cut out is automatically determined, and the set cutting line is automatically determined around the at least one object to be cut out. In one advantageous embodiment, the associated laser cutting line is also produced automatically.